

FIG. 1A

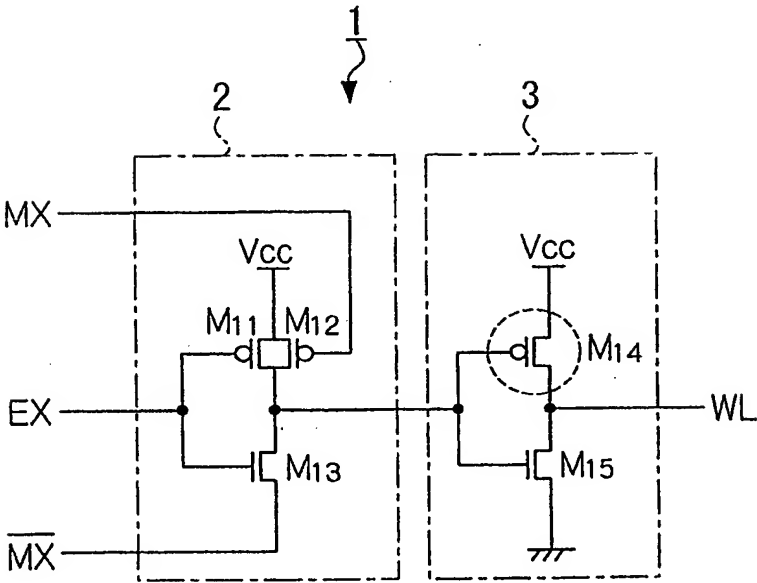


FIG. 1B

EX	MX	$\overline{MX}$	WL
0	0	1	0
0	1	0	0
1	0	1	0
1	1	0	1

FIG. 2A

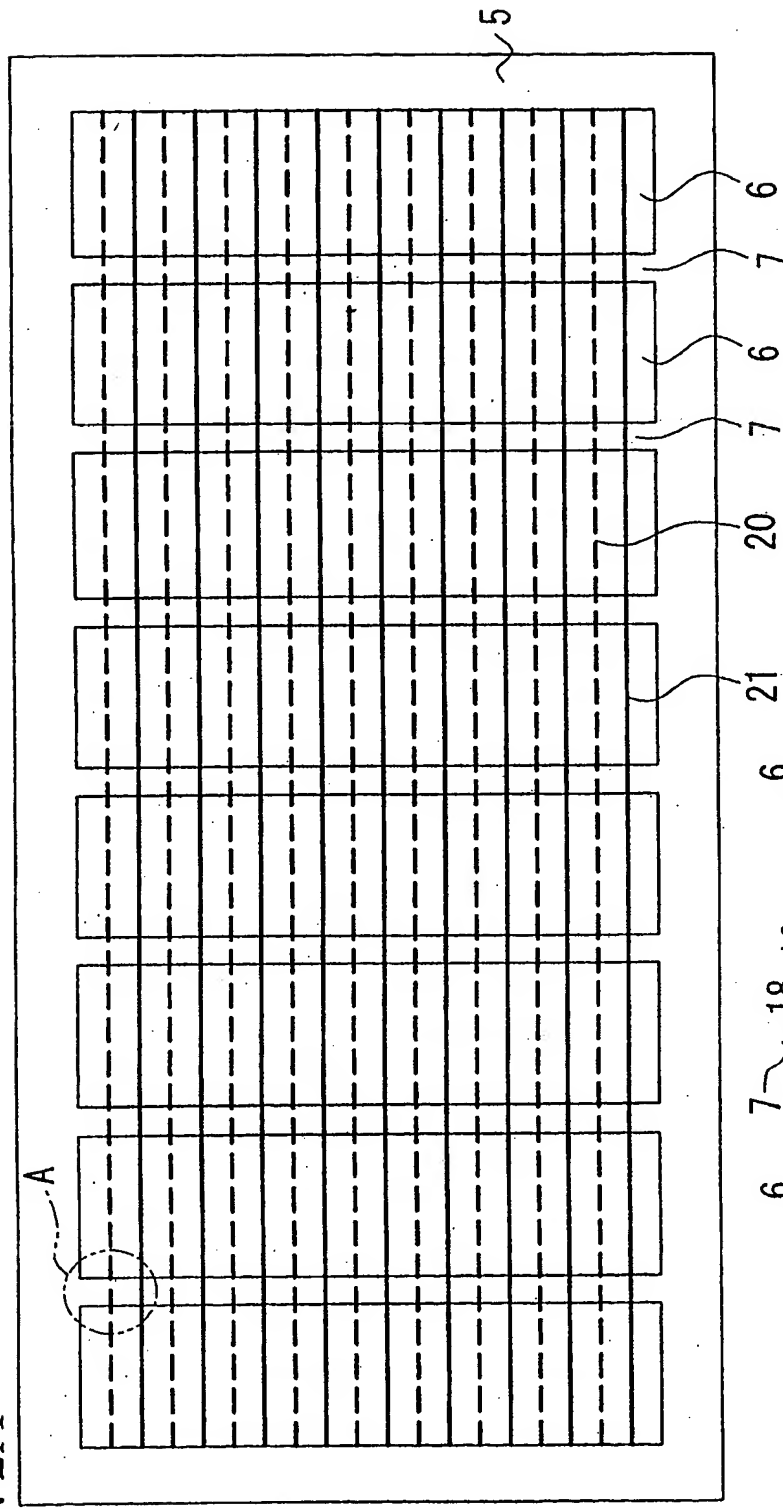


FIG. 2B

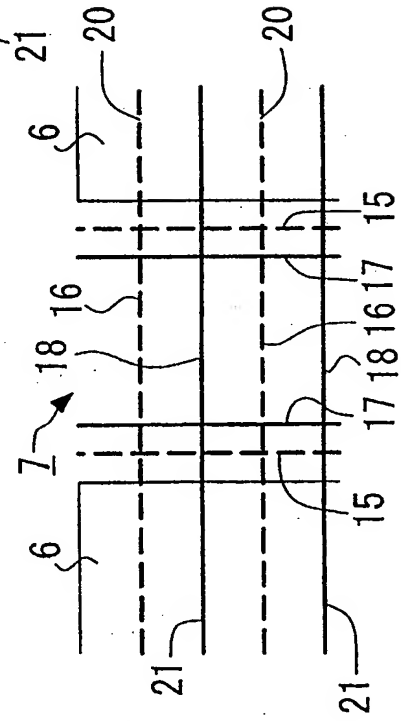


FIG. 3

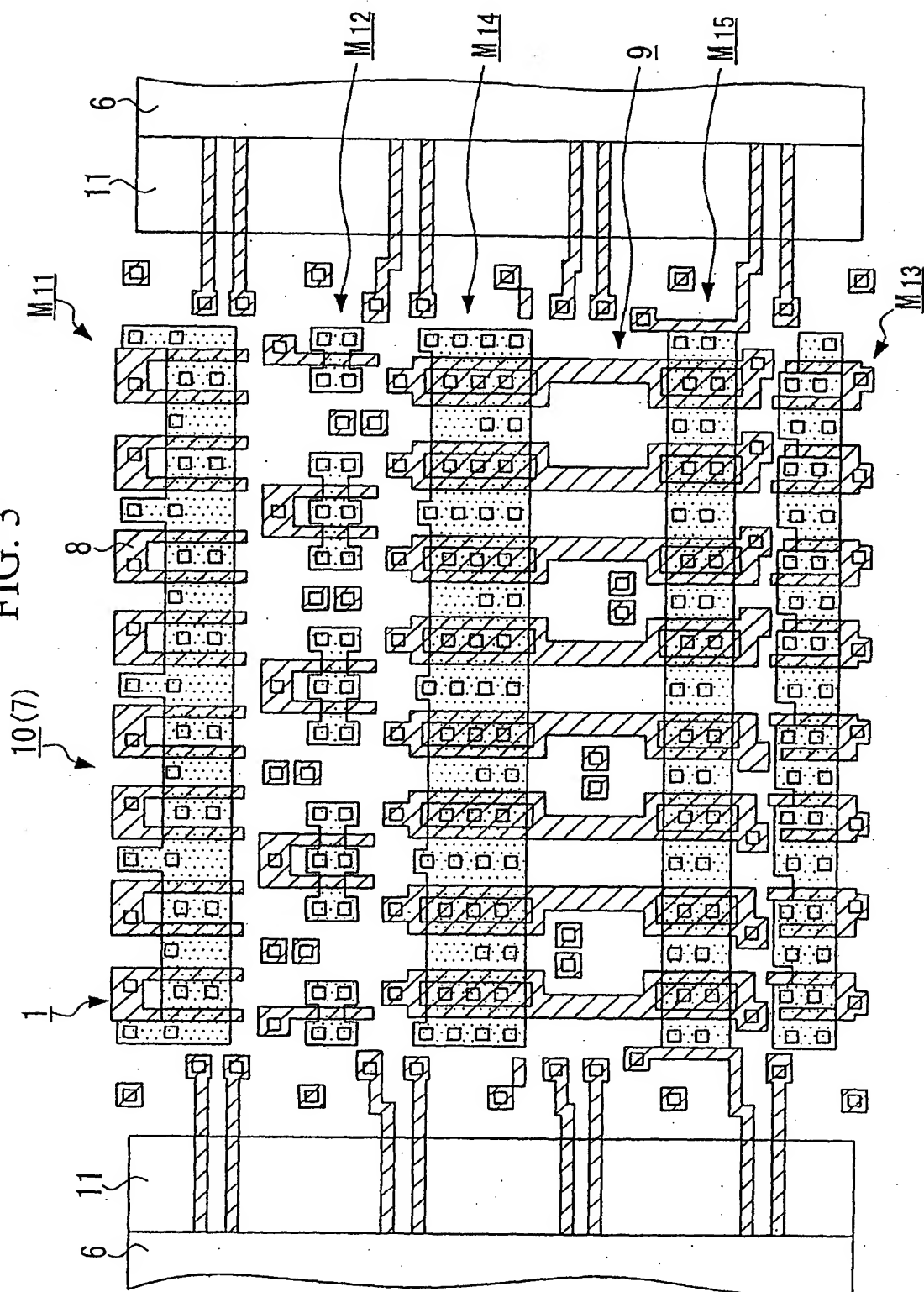


FIG. 4

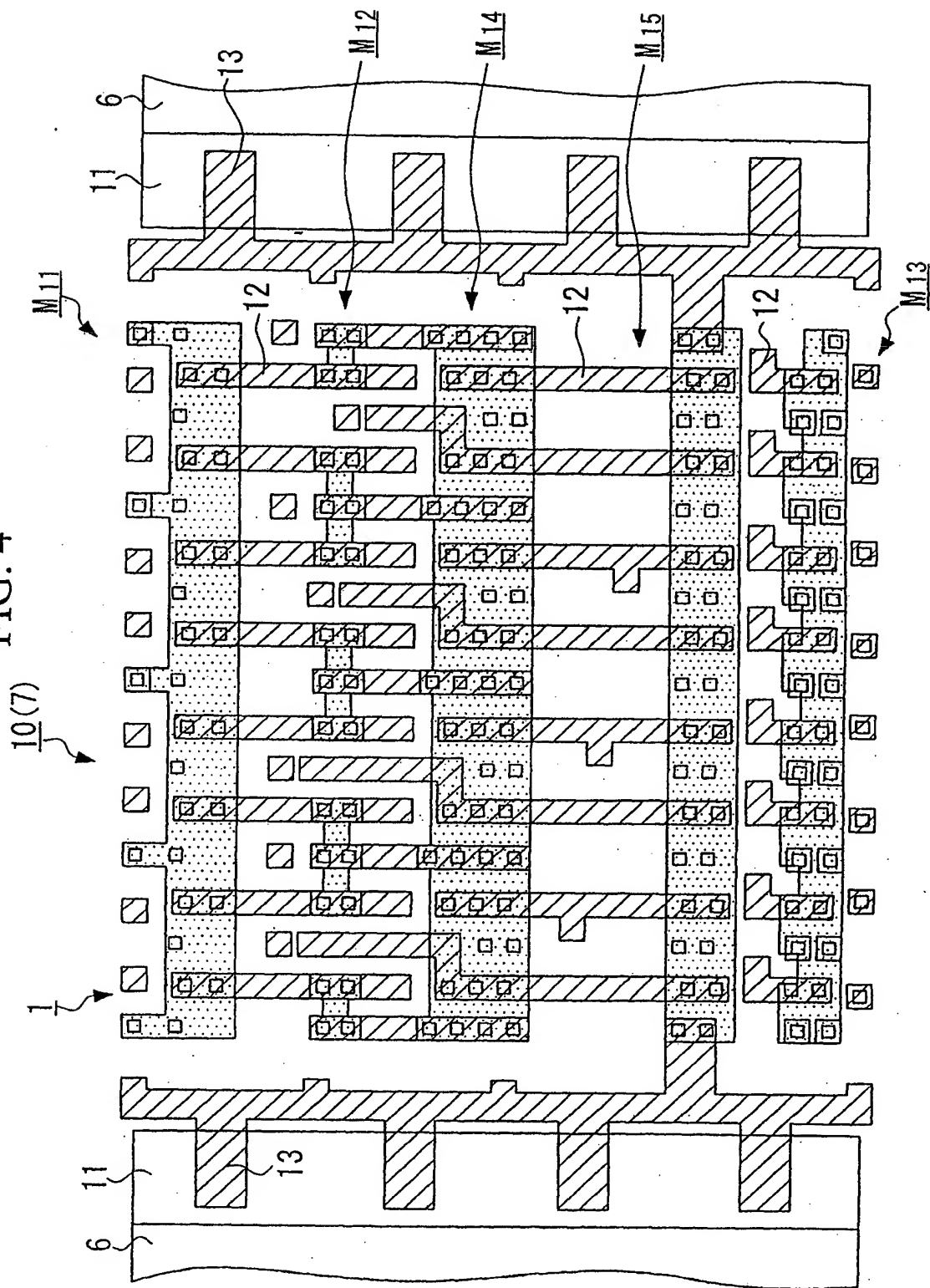
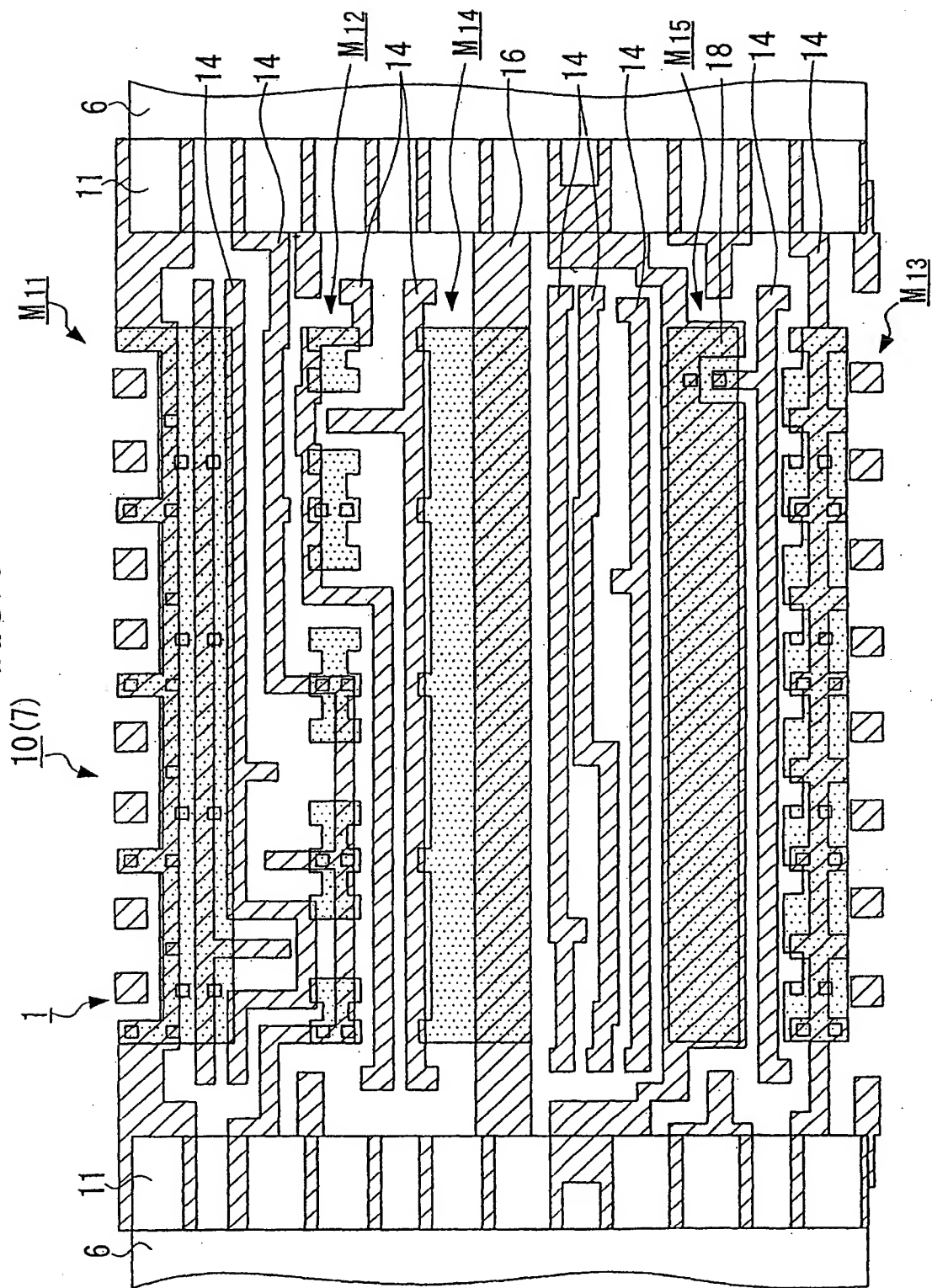


FIG. 5



This cross-sectional diagram illustrates a complex multi-layered structure, likely a printed circuit board or semiconductor package. The assembly consists of several distinct layers and components:

- Top Layer (6):** A thin, wavy topmost layer.
- Substrate (11):** A thick, hatched layer directly beneath the top layer.
- Core Layers (M11-M15):** Five horizontal layers labeled M11 through M15, each with a different pattern (diagonal lines, dots, or solid). These are separated by vertical interconnect structures (19).
- Interconnect Structures (19):** Vertical columns of material connecting the core layers, featuring a stepped profile.
- Bottom Layer (17):** A thick, hatched layer at the base of the core stack.
- Base Layer (15):** A thick, hatched layer at the very bottom of the assembly.
- Labels:** Various numerical labels (6, 11, 15, 17, 19) identify specific layers or features, while letters M11-M15 label the core layers.

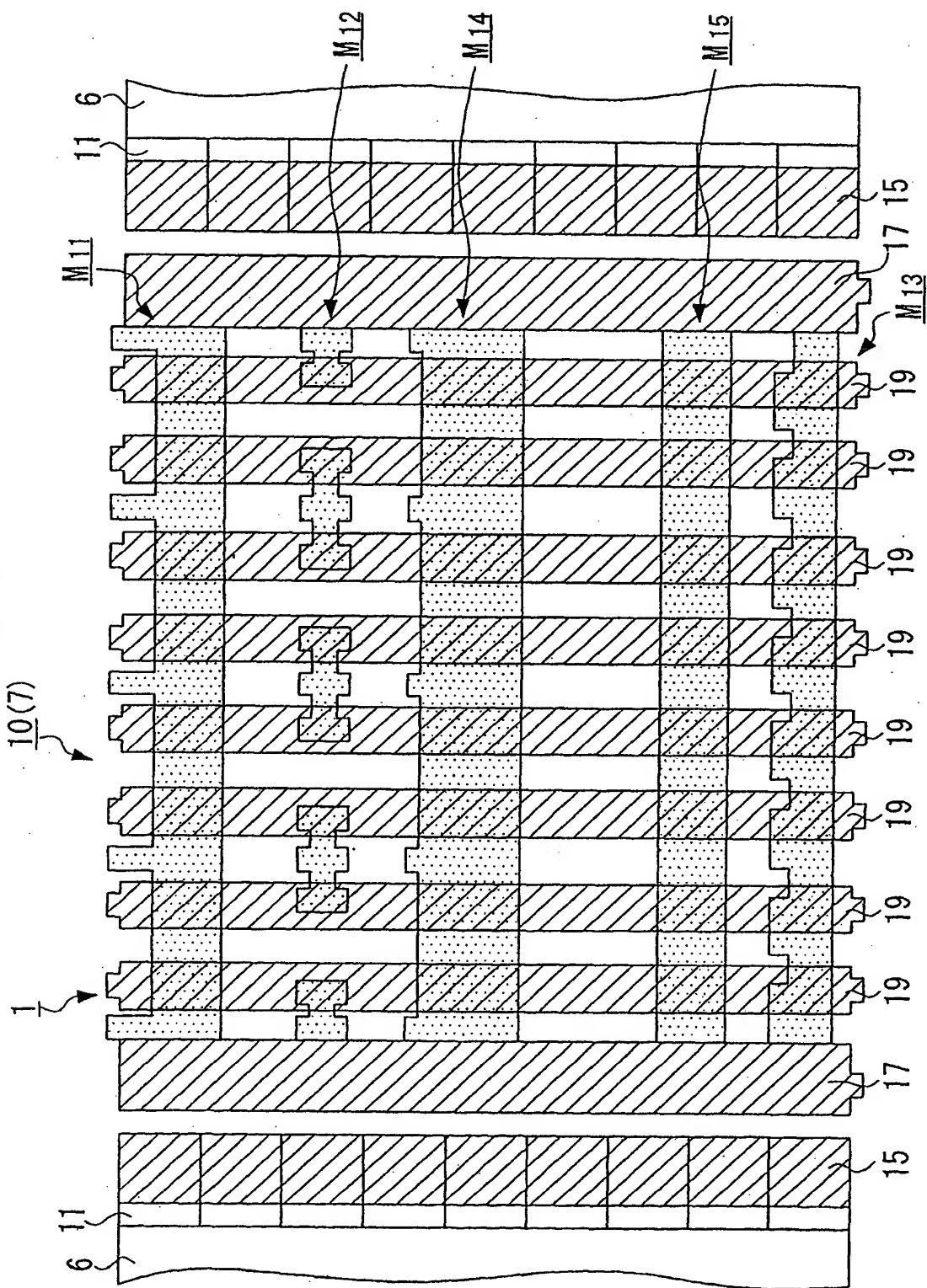


FIG. 7

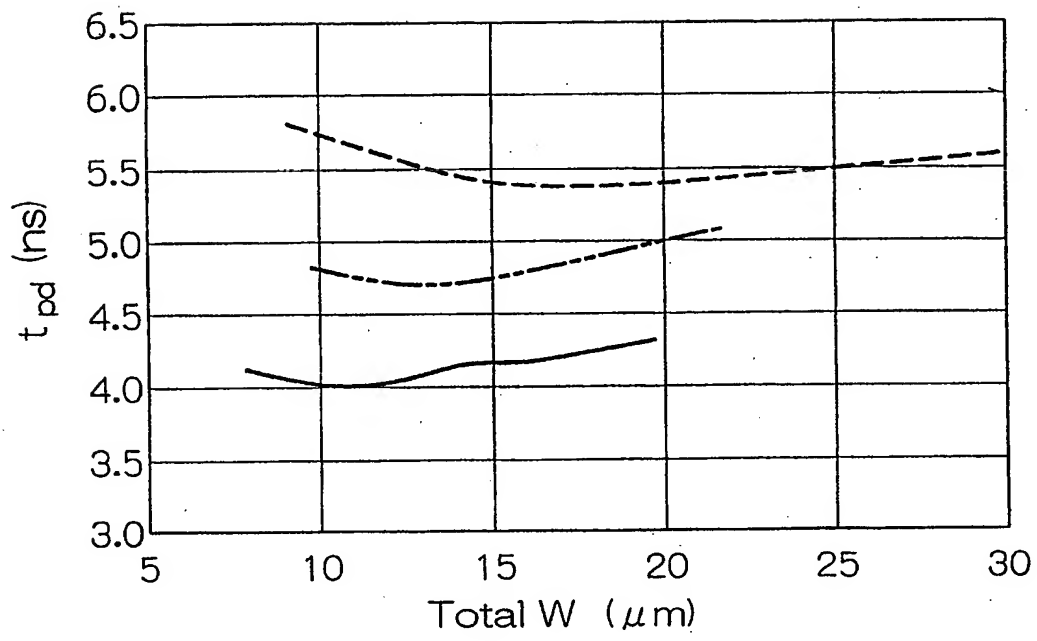


FIG. 8A

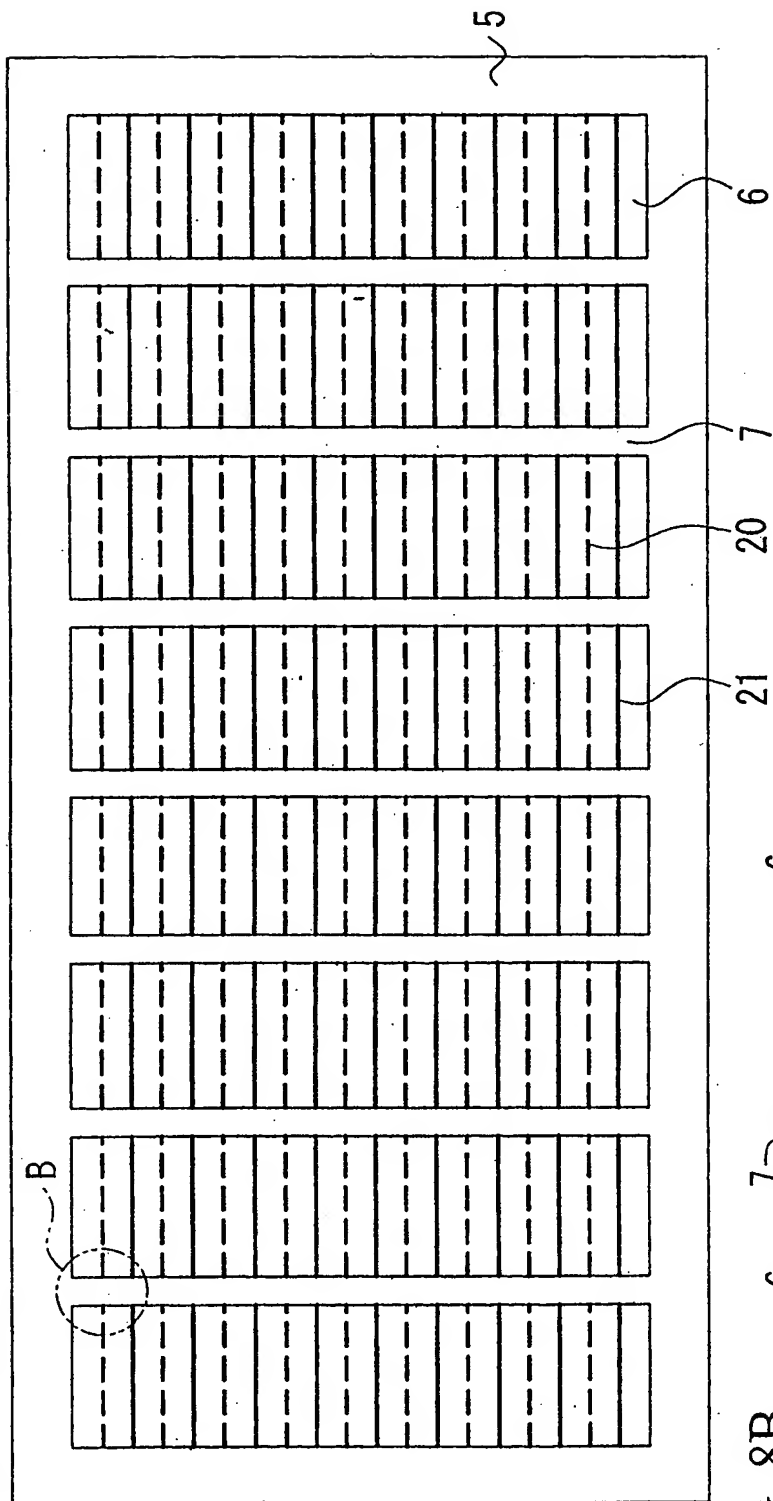


FIG. 8B

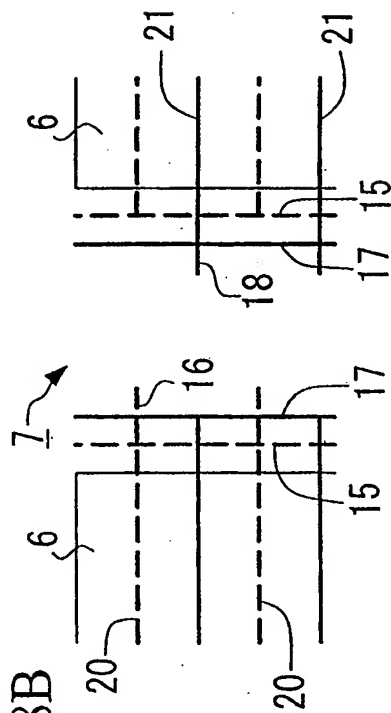




FIG. 9

10(7)

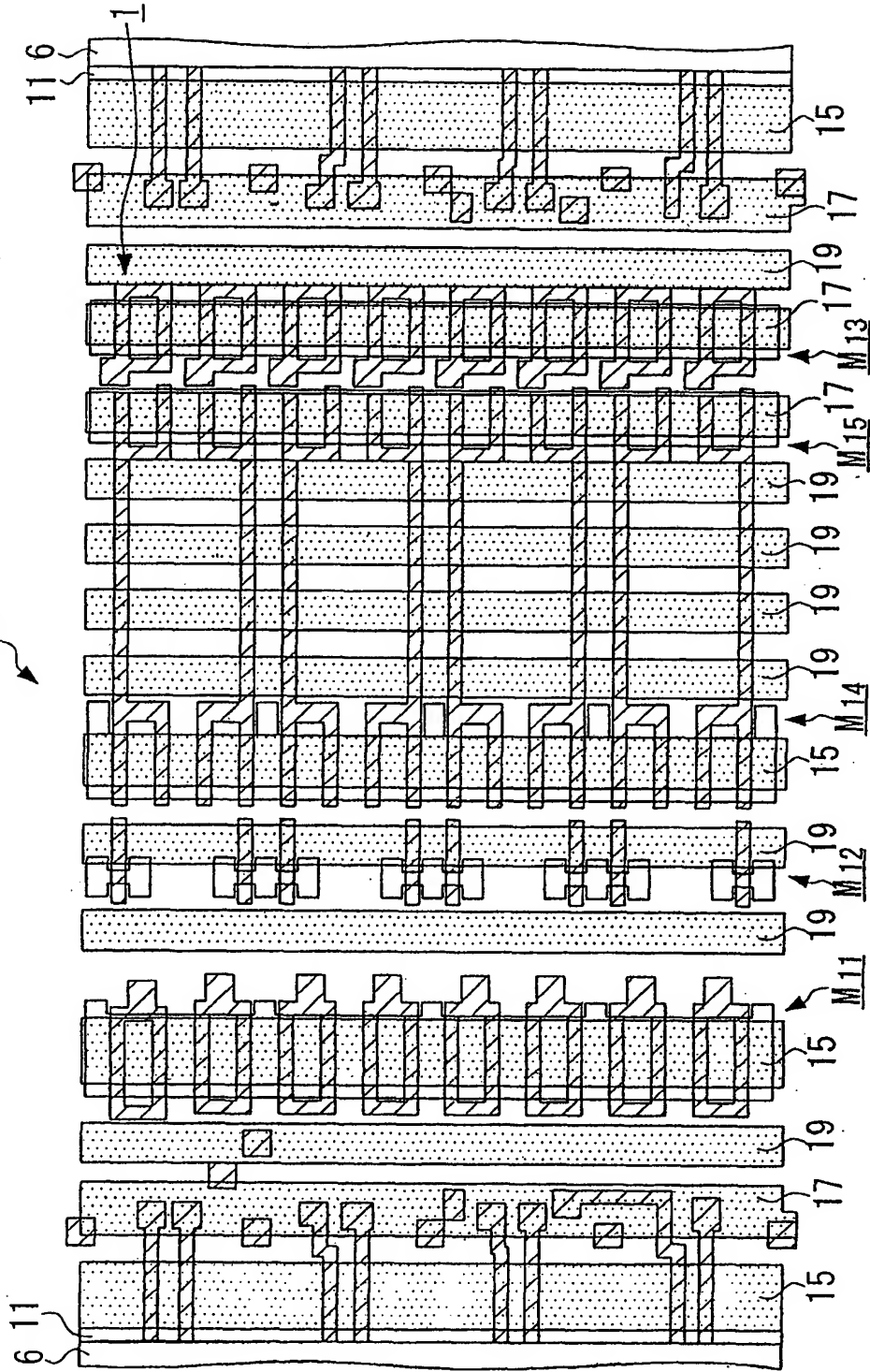


FIG. 10A

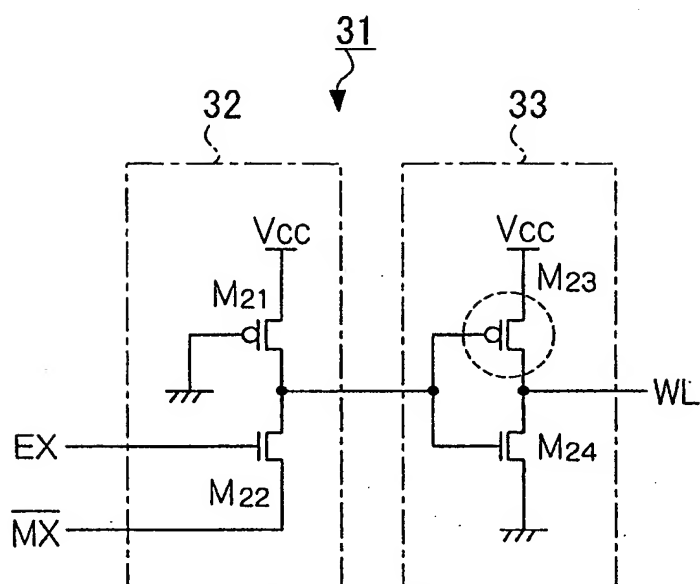


FIG. 10B

EX	MX	$\overline{MX}$	WL
0	0	1	0
0	1	0	0
1	0	1	0
1	1	0	1

FIG. 11A

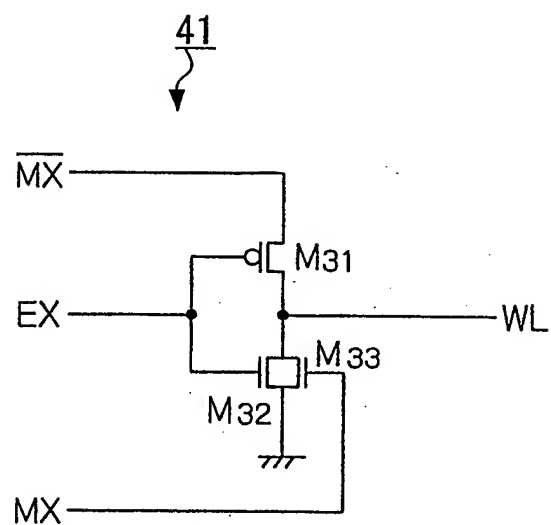


FIG. 11B

EX	MX	$\overline{MX}$	WL
0	0	1	1
0	1	0	0
1	0	1	0
1	1	0	0

FIG. 12

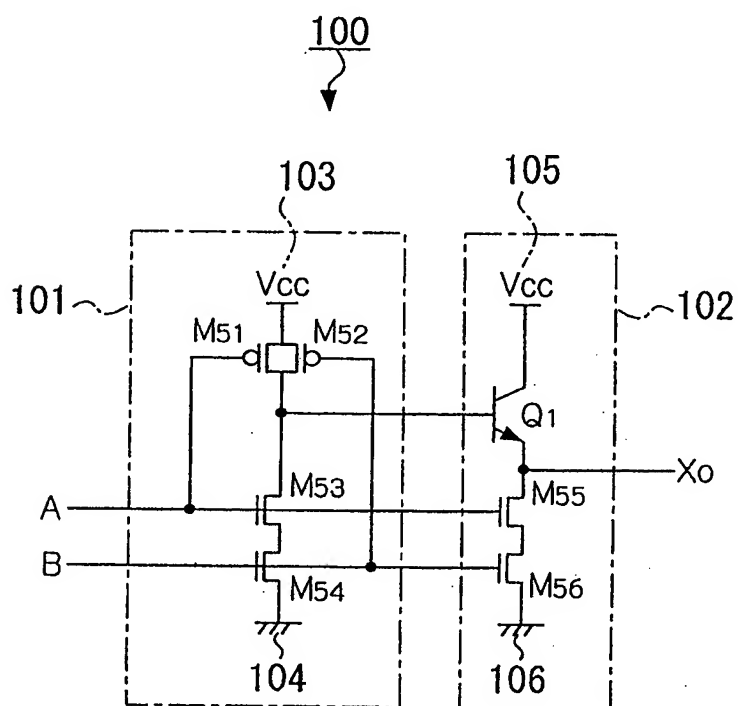


FIG. 13

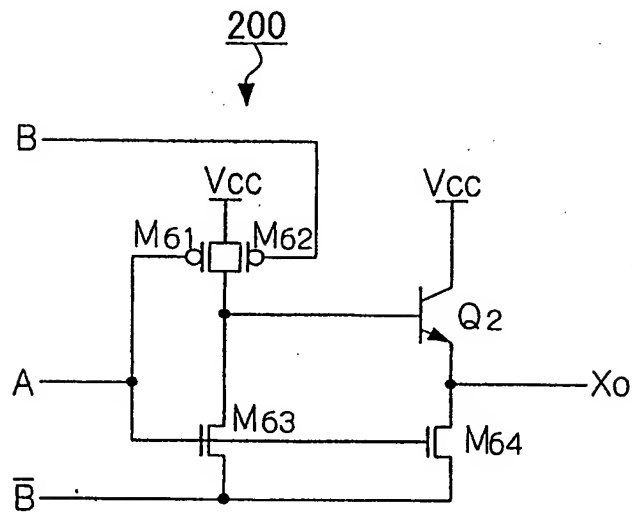


FIG. 14

